G2C+
T STRATEGY ALLIANCE

5443.TW GPM均豪

6640.TW GMM均華

C Sun Mfg Ltd.

Stock No. 2467.TW
c sun志聖

Investor's Meeting
2025.9.12

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements“. C Sun cautions readers that forward looking statements are based on C Sun’s reasonable knowledge and current expectations and are subject to various risks and uncertainties.

- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicality, customer’s financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun’s business and operations.

- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.

Business Philosophy- ALL WIN

G2C+

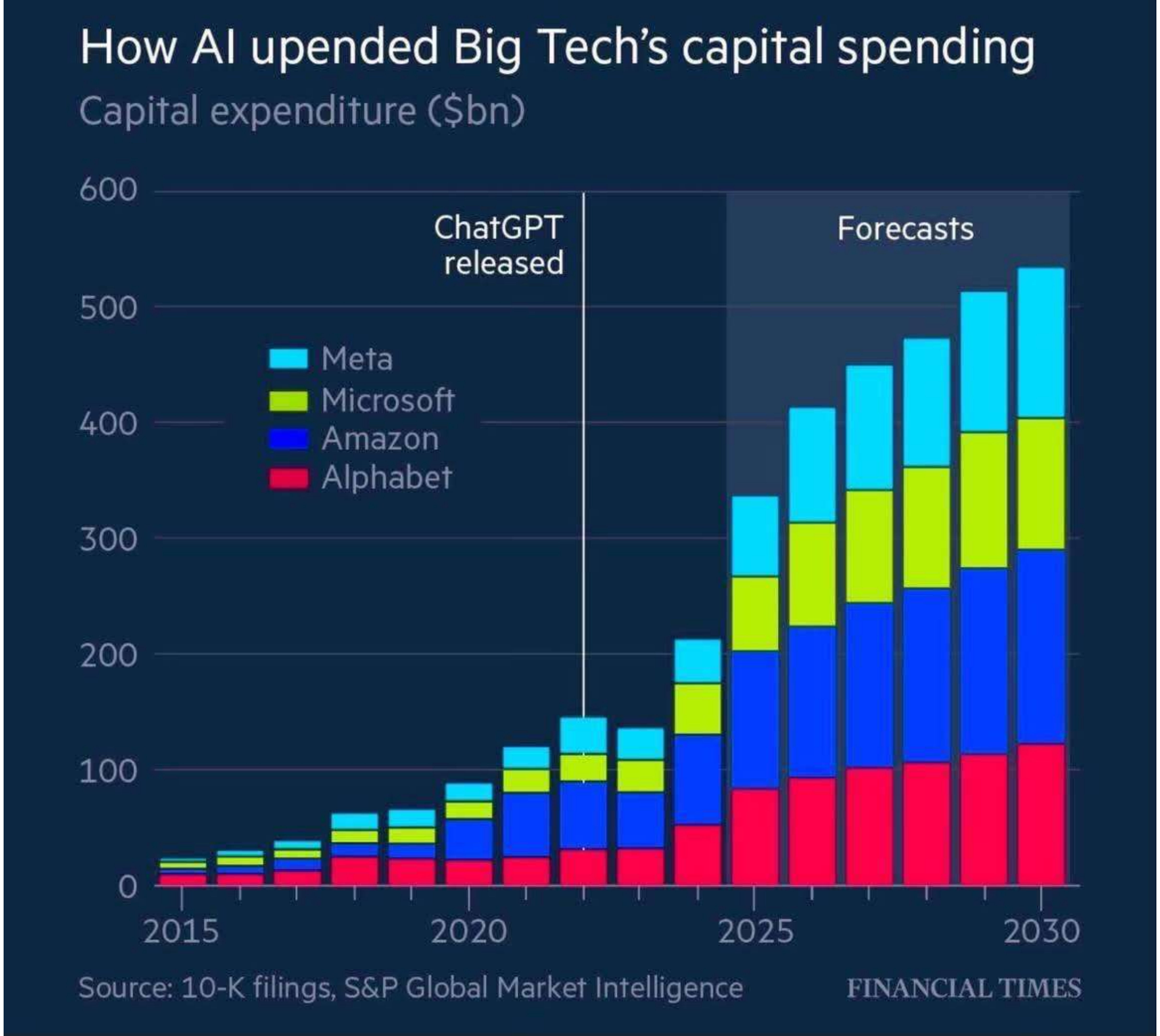
合力共創 同行致遠

Well-intentioned motives lead careers to success

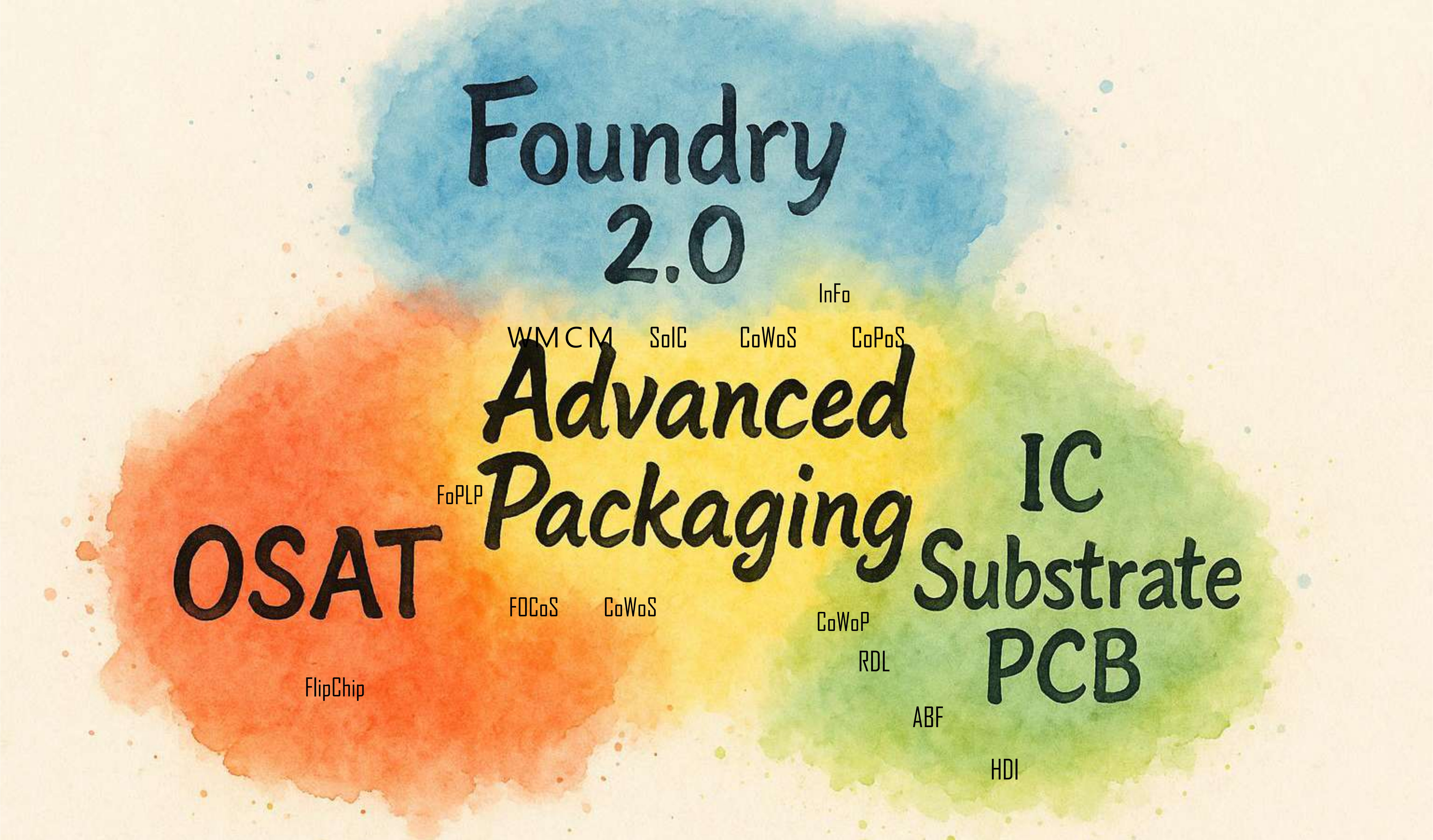
--- From 『Heart』 Inamori Kazuo ---

乘勢而上的AI浪潮

Riding the AI Wave



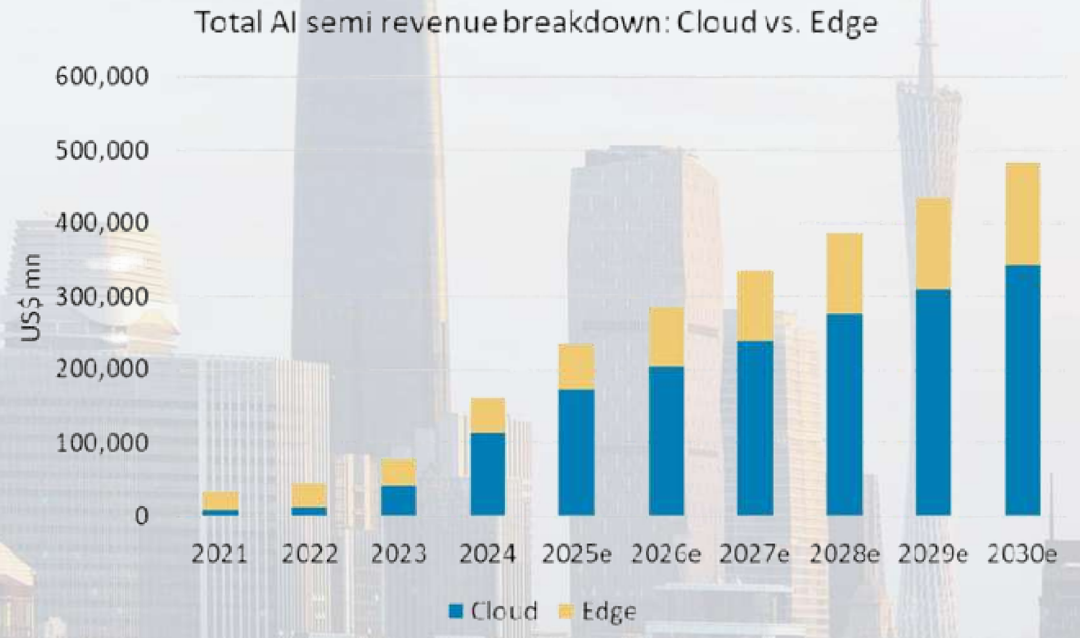
How AI upended Big Tech's capital spending
Capital expenditure ($bn)
600
500
400
300
200
100
0
ChatGPT released
Forecasts
Meta
Microsoft
Amazon
Alphabet
2015
2020
2025
2030
Source: 10-K filings, S&P Global Market Intelligence
FINANCIAL TIMES


Foundry
2.0
InFo
WMCM
SoIC
CoWoS
CoPoS
Advanced
Packaging
FoPLP
OSAT
IC
Substrate
PCB
FOCoS
CoWoS
CoWoP
RDL
FlipChip
ABF
HDI

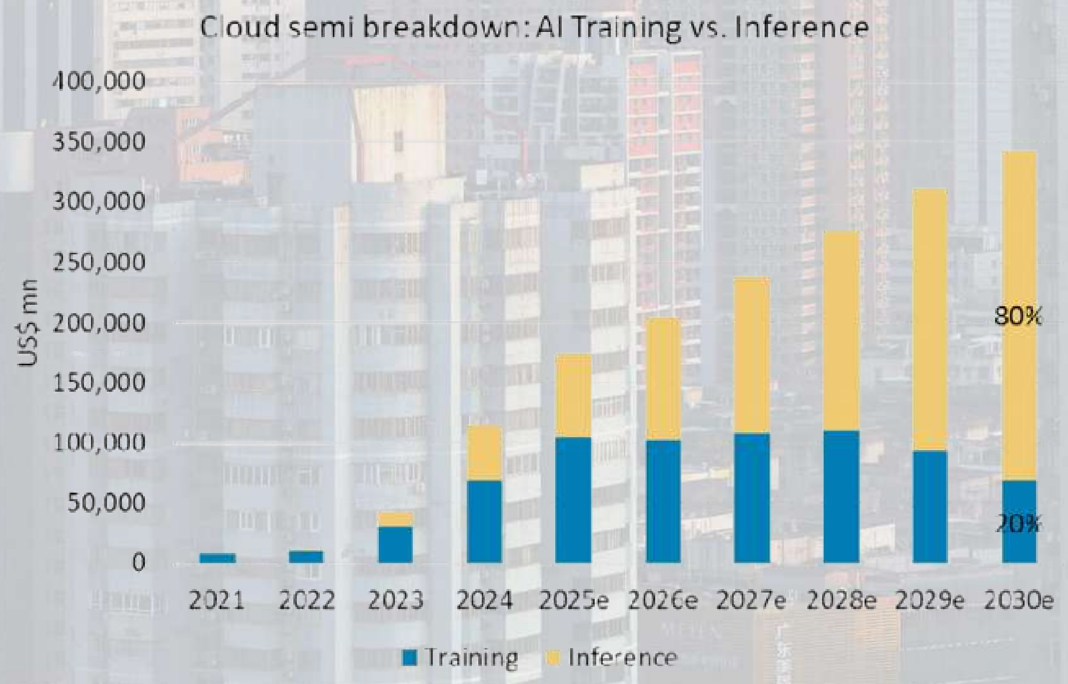
2025 Update: Our Forecasts For AI Semis Toward 2030e

- Growth perspective:
  1. Edge AI semis: 22% CAGR, 2023-30
  2. Inference AI semis: 55% CAGR, 2023-30
  3. **Custom AI semis: 39% CAGR**, 2023-30

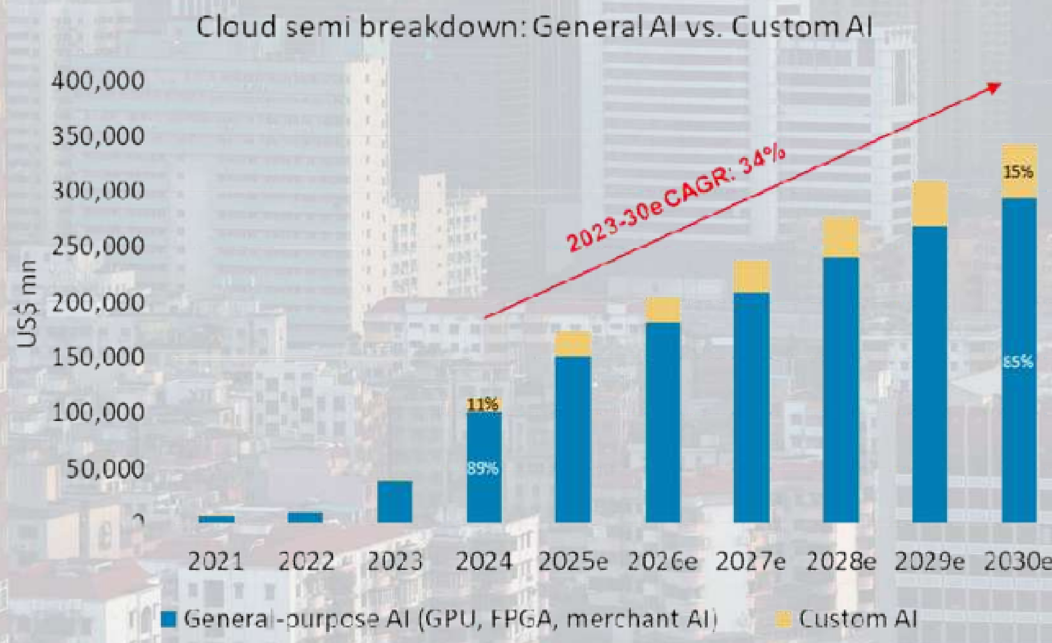
Edge AI semis could grow slightly faster than cloud



Within Cloud AI, Inference AI chips to outgrow training…



… and Custom AI chips to outgrow general purpose



Source: Company data, Gartner, Morgan Stanley Research (e) estimates.

Company Introduction

皆大歡喜

Success for ALL

Establishment: 1966.9.28

Capital: NT$1.56 billion

Chairman: Morrison Liang

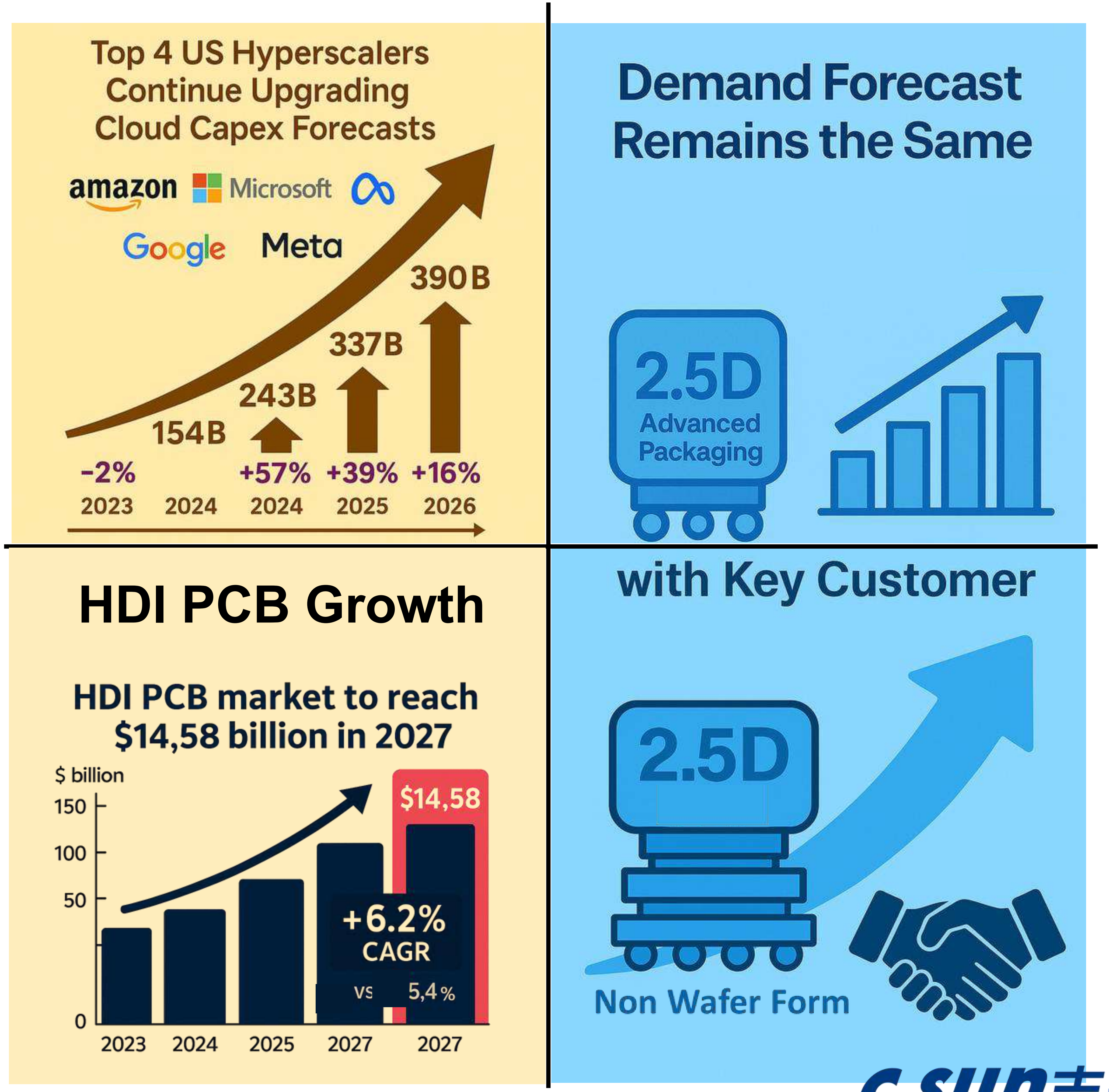
President: Frank Liang

Tariffs & FX Impact on Revenue and Margin

➤ **Tariffs: 1% Revenue Shipped to USA │ FOB-based**

➤ **FX: ~10% USD demonination│ NTD +1% → -0.06% GM**

Business goals continue and follow the technological development of leading customers



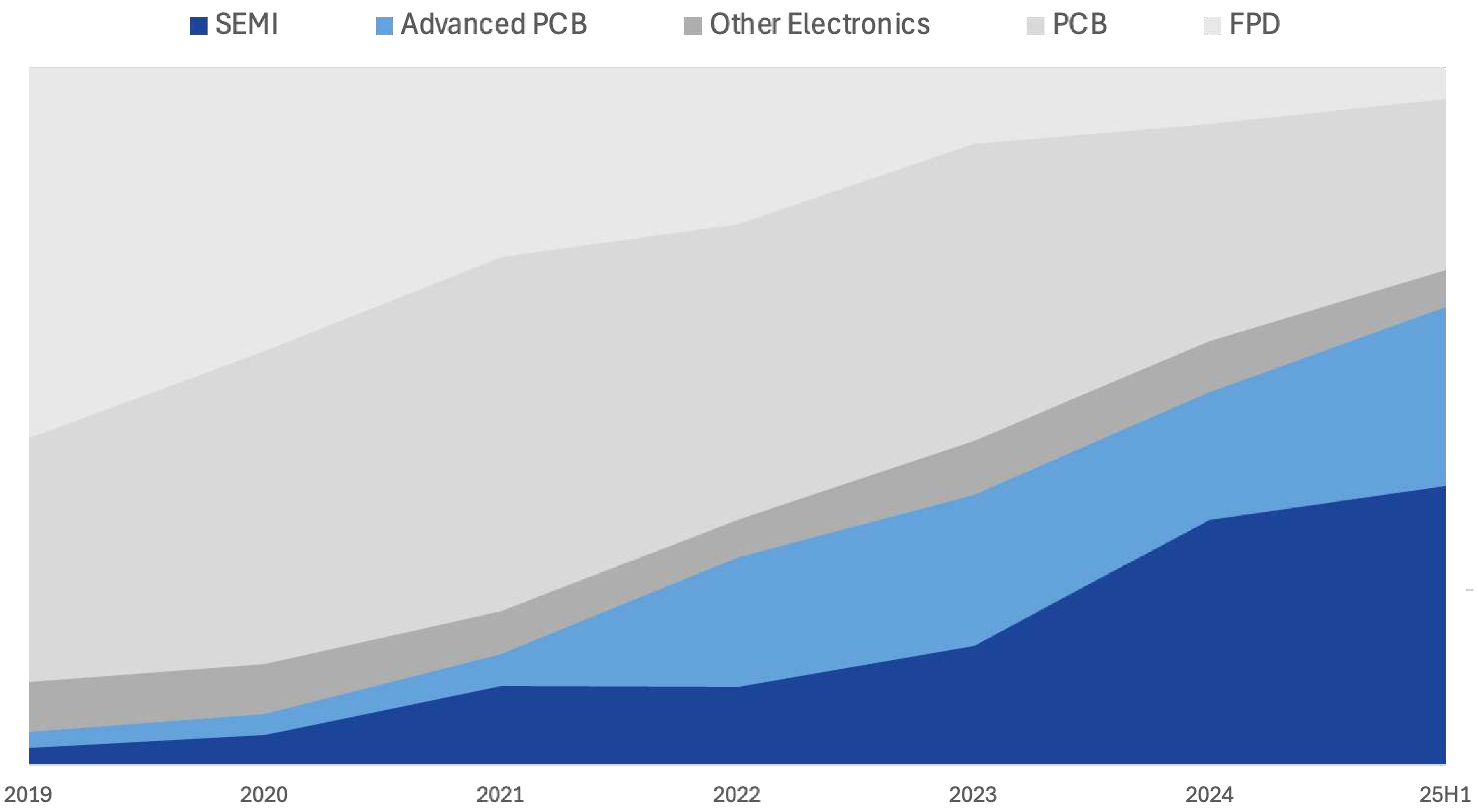
Financial Review

Selected Items from Statements of Comprehensive Income *(In NT$ millions unless otherwise noted)*	2Q25	1Q25	2Q24	QoQ	YoY
Revenue-Consolidated	1,510	1,309	1,349	15.4%	11.9%
Gross Margin%	**41.8%**	**43.0%**	**38.0%**	**-1.2ppts**	**+3.8ppts**
Operating Expense	(358)	(383)	(336)	-6.5%	7%
Operating Expense%	**23.7%**	**29.2%**	**24.9%**	**-5.5ppts**	**-1.2ppts**
Operating Margin%	**18.1%**	**13.8%**	**13.1%**	**+4.3%**	**-0.5ppts**
Non-Operating Items	(5)	59	64	-109%	-108%
Net Income Attributable to Shareholders of the Parent Company	207	150	187	38%	11%
Net Profit Margin%	**13.7%**	**11.5%**	**13.9%**	**+2.2ppts**	**-0.2ppts**
EPS (NT$D)	1.37	1	1.25	37%	10%

1H25 Revenue YoY +16.1%, Gross Margin YoY +2 ppts

C SUN志聖

Revenue Composition



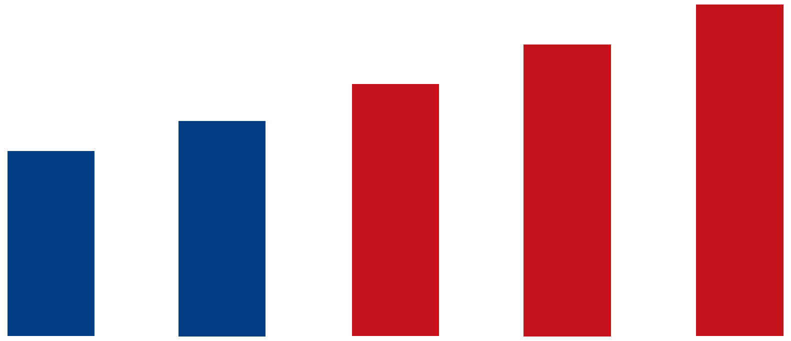
SEMI~40%

Gross Margin Rate

OSATs' Revenue Composition Growth

TOP 10 OSATs Are All Customers of G2C+

4%



10%

ASE · Amkor Technology · JCET · TF 通富微電 · PTI · HUA TIAN

KYEC · ChipMOS · CHIPBOND 頎邦科技


Focusing
AI聚焦
WMCM
LPO
HBM
oS
Assembly
IC Substrate
CoW
SoC/SoIC
CPO
Test
Mother Board
2025 H1
>65%
c sun志聖


Advanced
PCB
Advanced
Packaging
Lamination, Peeling,
Bonding & Thermal
4 Engines Driving
the Future of Semi × PCB
Veo

G2C+
T STRATEGY ALLIANCE

The Alloance Members: 1700+

R&D personnel: 560+

R&D personnel account for 32.5%

Since 1966	Since 1978	Since 1978
C SUN志聖	GPM均豪精密	GMM均華精密
Thermal (熱) Bonder (壓合) Lamination (貼膜) Peeling (撕膜) UV/Plasma (光/電漿)	AOI (檢測) Metrology (量測) Grinding (研磨) Polishing (拋光)	Die Attach (黏晶) Chip Sorter (揀晶) Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

c sun
Bonder
Lamination
Peeling
Thermal

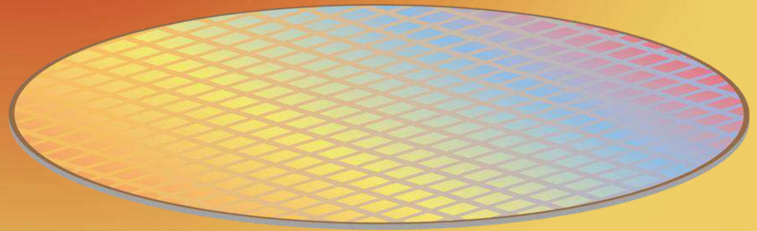
GPM
AOI
Metrology
Grinding
Polishing

GMM
Die Attach
Chip Sorter
Auto Jig Saw

Advanced packaging

IC Substrate 、 HBM Packaging 、 2.5/3DIC

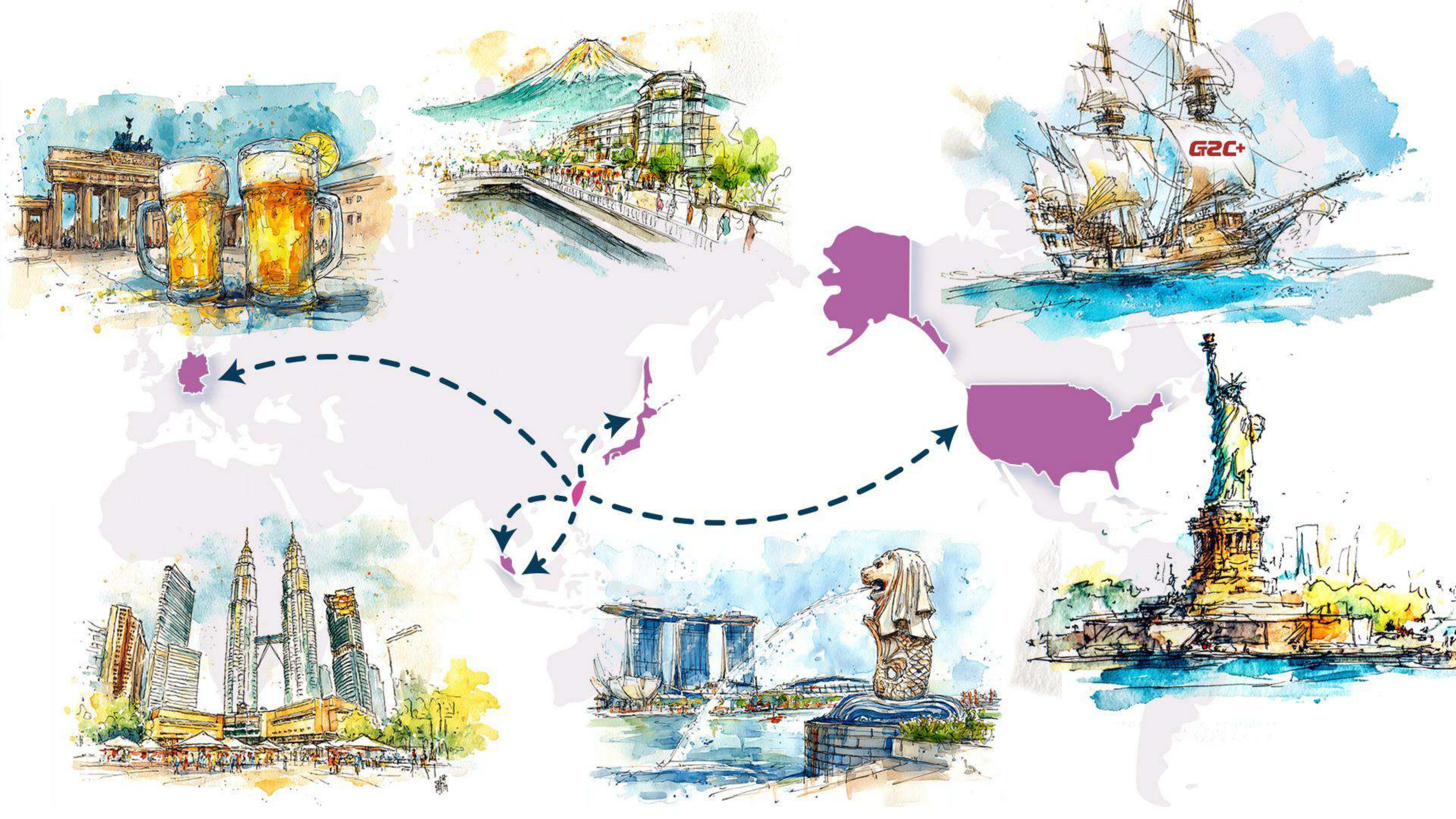
G2C+
T STRATEGY ALLIANCE



c sun GPM

Foundry

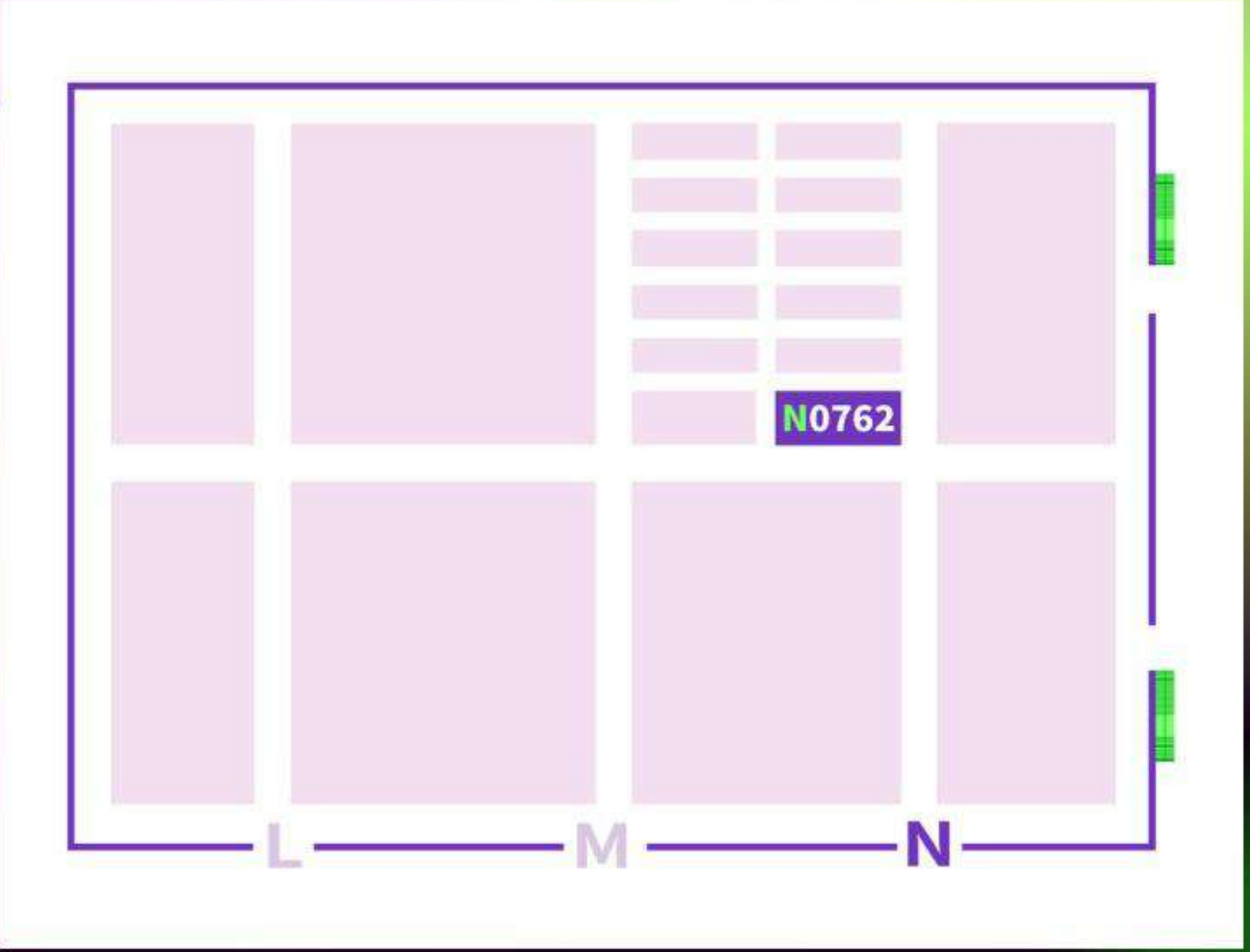
Reclaim wafer


G2C+

SEMICON® TAIWAN
國 際 半 導 體 展
Breaking Limits: Powering the AI Era.

2025
9/10~12
TAIPEI NANGANG EXHIBITION CENTER,
HALL 1 4F N0762

Invitation



Dear Esteemed Industry Leaders:

We cordially invite you to visit 4th Floor NO762 of TaiNEX. A dedicated specialist will be on hand to guide you through our comprehensive smart solutions to enhance and optimize your production line performance.

Your trust and support are the driving force behind our shared success and innovation.

G2C+ T STRATEGY ALLIANCE | C SUN志聖 GPM均豪精密 GMM均華精密

C SUN

A G2C+ Alliance Company

Thank you for your attention